

DOCKET NO. 99-102/1D

Express Mailing Label No. ET662218667US

4/Pre Amndt A
Ca
6/5/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: : Wilbur G. Catabay and Richard Schinella
Appl. No. : Division of Serial No. 09/426,056
Filed: : Herewith
Title : LOW K DIELECTRIC COMPOSITE LAYER FOR INTEGRATED
CIRCUIT STRUCTURE WHICH PROVIDES VOID-FREE LOW K
DIELECTRIC MATERIAL BETWEEN METAL LINES WHILE
MITIGATING VIA POISONING
Grp./ A.U. : 2813
Examiner : Lisa Kilday
Docket No. : 99-102/1D

PRELIMINARY AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Date: March 15, 2002

Sir:

Please amend the accompanying divisional application as follows: